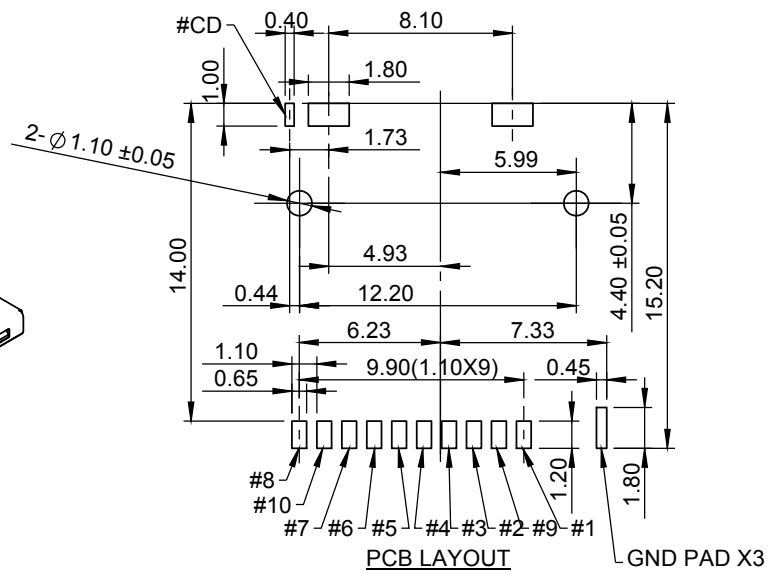
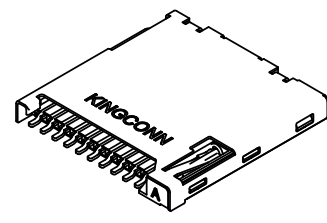
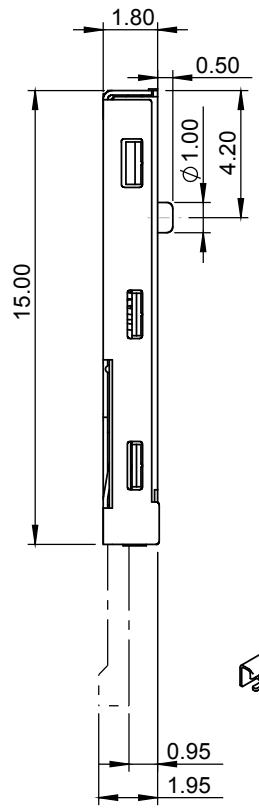
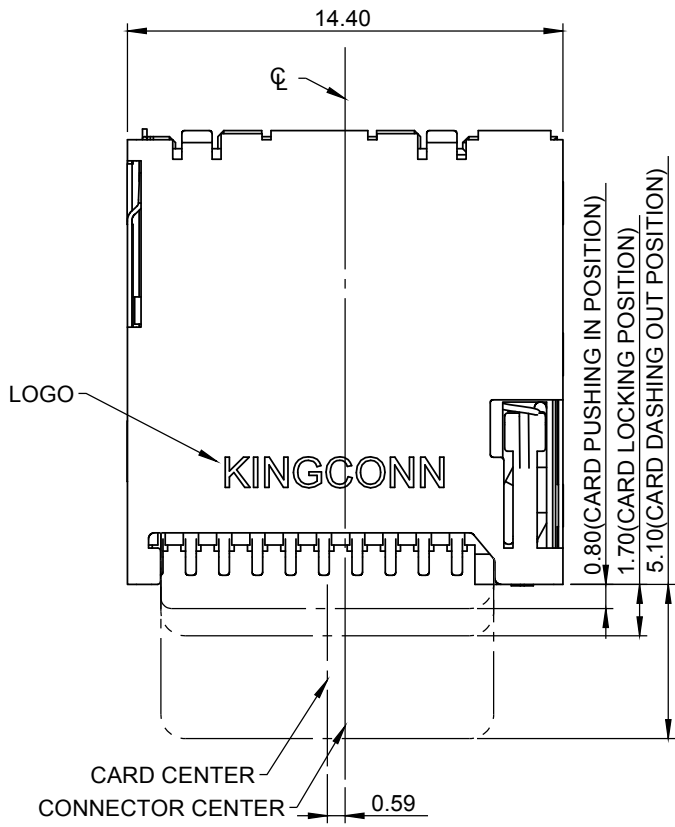


NOTES:
 1. MATERIAL:
 INSULATOR: HIGH TEMPERATURE THERMOPLASTIC,
 UL94V-0, BLACK
 CONTACT: PHOSPHOR BRONZE
 2. PART NO: 7MSDP-X0-2 X X 0

更改 REV	設 變 內 容 MODIFICATION
F	ECN02840
G	ECN03445
H	ECN04062

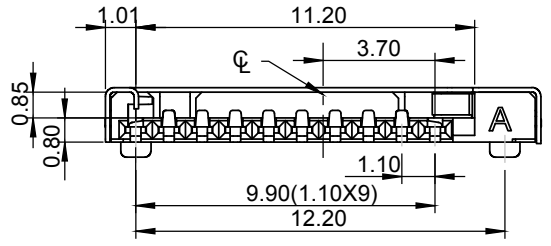
0: WITHOUT LOGO
 1: WITH LOGO
 1: REEL
 2: TRAY

PLATING :
 F CONTACT AREA : Gold Flash PLATED OVER Ni
 SOLDER AREA : Matte Tin PLATED OVER Ni
 B CONTACT AREA : 10μ" Au PLATED OVER Ni
 SOLDER AREA : Matte Tin PLATED OVER Ni



RECOMMEND P.C.B LAYOUT
 TOLERANCE ±0.05mm

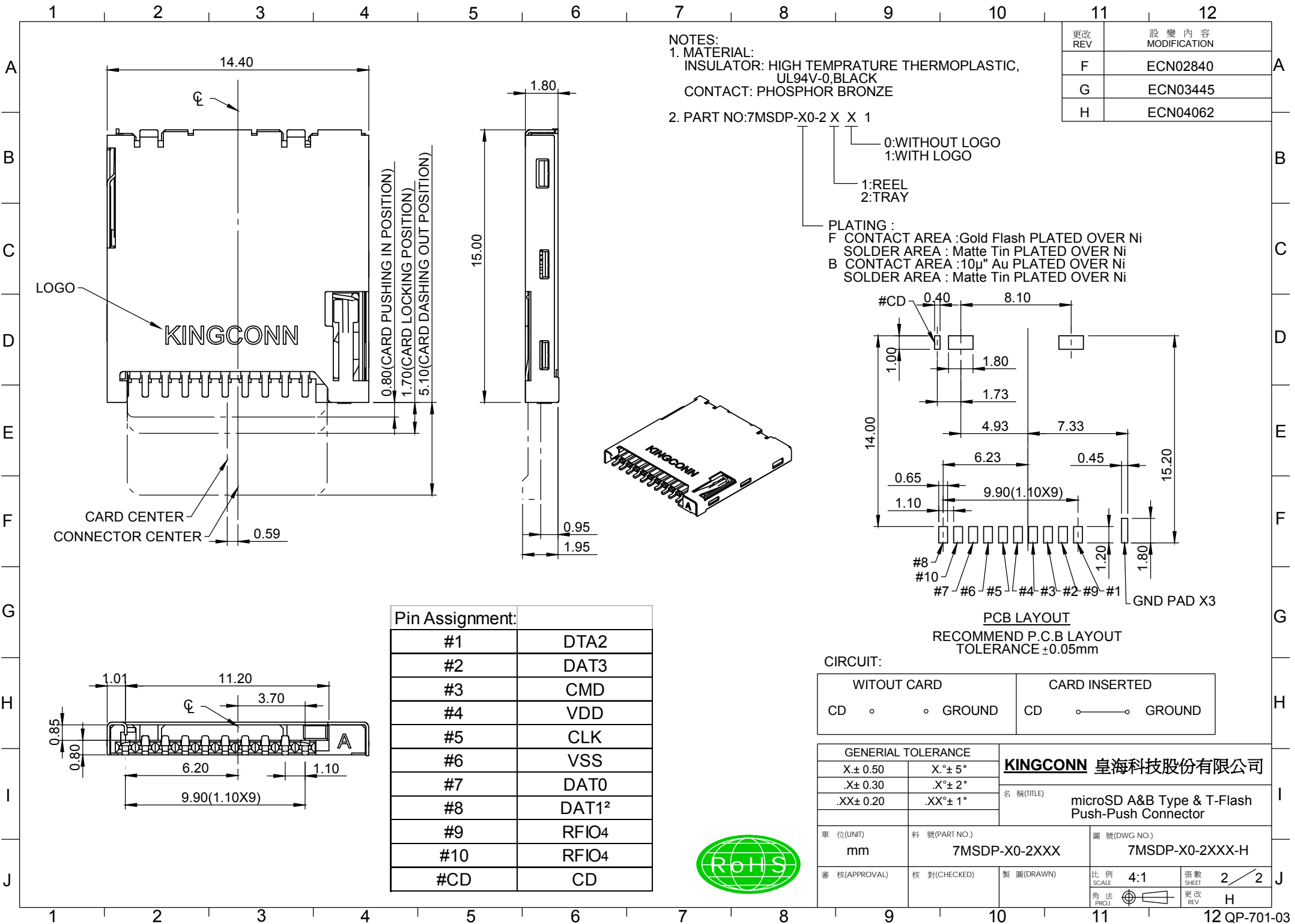
CIRCUIT:



Pin Assignment:	
#1	DTA2
#2	DAT3
#3	CMD
#4	VDD
#5	CLK
#6	VSS
#7	DAT0
#8	DAT1 ²
#9	RFIO4
#10	RFIO4
#CD	CD



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X ± 0.50	X° ± 5°		
.X ± 0.30	.X° ± 2°		
.XX ± 0.20	.XX° ± 1°	名稱(TITLE) microSD A&B Type & T-Flash Push-Push Connector	
單位(UNIT) mm	料 號(PART NO.) 7MSDP-X0-2XXX	圖 號(DWG NO.) 7MSDP-X0-2XXX-H	
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 4:1
			張 數 SHEET 1 / 2
			更 改 REV H

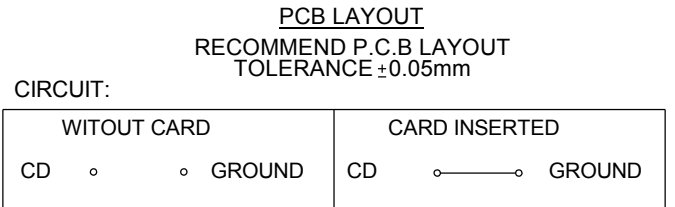
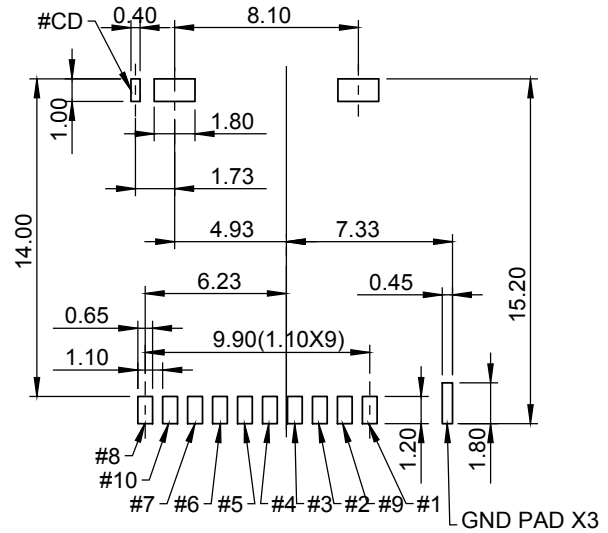


NOTES:
 1. MATERIAL:
 INSULATOR: HIGH TEMPERATURE THERMOPLASTIC,
 UL94V-0, BLACK
 CONTACT: PHOSPHOR BRONZE
 2. PART NO: 7MSDP-X0-2 X X 1

更改 REV	設 變 內 容 MODIFICATION
F	ECN02840
G	ECN03445
H	ECN04062

0: WITHOUT LOGO
 1: WITH LOGO
 1: REEL
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PLATING :
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Pin Assignment:	
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GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X ± 0.50	X ° ± 5°	名稱(TITLE) microSD A&B Type & T-Flash Push-Push Connector	
.X ± 0.30	.X ° ± 2°		
.XX ± 0.20	.XX ° ± 1°		
單位(UNIT) mm	料 號(PART NO.) 7MSDP-X0-2XXX	圖 號(DWG NO.) 7MSDP-X0-2XXX-H	
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 4:1
			張 數 SHEET 2 / 2
			角 法 PROJ.
			更 改 REV H